

EMI AND RFI SHIELDING FOR PRINTED CIRCUIT BOARDS

ABSTRACT OF THE DISCLOSURE

The present invention provides a vacuum deposited metal layer that can shield the electronic components on a PCB or FPC. The vacuum metallized conductive layer can be grounded to a ground trace on the circuit board to create a Faraday cage to protect the electronic components disposed on the circuit board from EMI. The metallized conductive layer can be disposed over an encapsulating insulative layer or onto a shaped thermoform or mold injected plastic substrate that is coupled to the PCB or FPC.

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